

# Harvatek Surface Mount CHIP LEDs Data Sheet B2601UYG-20C001023E0118

Official Product	Official Product HT Part No. B2601UYG-20C001023E0118				
Tentative Product	*******				
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, company confidential all rights reserved.		09/18/2023	Version 1.3	Page 1/14	



DISCLAIMER3	
LIFE SUPPORT POLICY3	
PRODUCT SPECIFICATIONS4	
ATTENTION: ELECTROSTATIC DISCHARGE (ESD) PROTECTION4	
LABEL SPECIFICATIONS5	
SPECIFICATIONS RANGE6	
PRODUCT FEATURES7	
ELECTRO-OPTICAL CHARACTERISTICS7	
PACKAGE OUTLINE DIMENSION AND RECOMMENDED SOLDERING PATTERN FOR REFLOW SOLDERING	C
ABSOLUTE MAXIMUM RATINGS	
PRECAUTION FOR USE9	
PACKAGING10	
Tape Dimension10	
REEL DIMENSION11	
Packing11	
DRY PACK12	
BAKING12	
Precautions	
REFLOW SOLDERING13	
REWORKING13	
CLEANING13	
Cautions of Pick and Place14	
Revise History14	

7				
Official Product	HT Part No. B2601UYG-20C001023E0118			
Tentative Product	*******			
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, company confidential all rights reserved.		09/18/2023	Version 1.3	Page 2/14



#### **DISCLAIMER**

HARVATEK reserves the right to make changes without further notice to any products herein to improve reliability, function or design. HARVATEK does not assume any liability arising out of the application or use of any product or circuit described herein; neither does it convey any license under its patent rights, nor the rights of others.

#### **Life Support Policy**

HARVATEK's products are not authorized for use as critical components in life support devices or systems without the express written approval of the President of HARVATEK or HARVATEK INTERNATIONAL. As used herein:

- 1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.
- 2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

7					
Official Product	HT Part No. B2601UYG-20C001023E0118				
Tentative Product	*******				
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, company confidential all rights reserved.		09/18/2023	Version 1.3	Page 3/14	



#### **Product Specifications**

Item	Specification	Material	Quantity
Luminous	UYG:28.5-180.0 mcd		
Intensity(Iv)	@20mA/ $T_s$ = 25°C; Tolerance: ±10%		
Wavelength	UYG:567.5-579.5 nm		
	@20mA/ $T_S$ = 25 $^{\circ}$ C; Tolerance: ±0.5nm		
Vf	UYG:1.6-2.4V		
	@20mA/ $T_S$ = 25°C ;Tolerance:±0.05V		
Ir	< 10 μA @ V <sub>R</sub> = 5 V		
Resin	Clear	Ероху	
Carrier tape	EIA 481-1A specs	Conductive black tape	
Reel	EIA 481-1A specs	Conductive black	
Label	HT standard	Paper	
Packing bag	250x230mm	Aluminum laminated bag/ no-zipper	One reel per bag
Carton	HT standard	Paper	Non-specified

#### Others:

Each immediate box consists of 5 reels. The 5 reels may not necessarily have the same lot number or the same bin combinations of Iv,  $\lambda_D$  and Vf. Each reel has a label identifying its specification; the immediate box consists of a product label as well.

Note: This is shipped test conditions

\*Remarks: This product should be operated in forward bias. If a reverse voltage is continuously applied to the product, such operation can cause migration resulting in LED damage.

#### ATTENTION: Electrostatic Discharge (ESD) protection



The symbol to the left denotes that ESD precaution is needed. ESD protection for GaP and AlGaAs based chips is necessary even though they are relatively safe in the presence of low static-electric discharge. Parts built with AlGaInP, GaN, or/and InGaN based chips are **STATIC SENSITIVE devices**. ESD precaution must

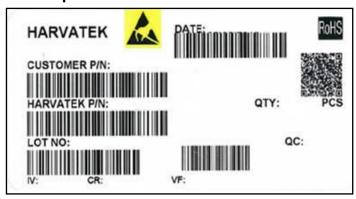
be taken during design and assembly.

If manual work or processing is needed, please ensure the device is adequately protected from ESD during the process.

Official Product	HT Part No. B2601UYG-20C001023E0118				
Tentative Product	*******				
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, company confidential all rights reserved.		09/18/2023	Version 1.3	Page 4/14	



# **Label Specifications**



#### **■**Harvatek P/N:

B 260 1 UYG- 20C- 0010 23

Product	Package	Dice Qty	Color	Current	Series Number	Taping
PCB	3.2(L)x1.2(W)x1.1(H) mm	1:Single	UYG: Ultra Bright	20mA	X001~XZZZ	1.Taping style
			Yellow Green			2. Qty

## ■ Lot No.:

1 2	3	4	5	6	7	8	9	10
E 1	Α	1	Α	2	2	L	1	2
Code 1 2	Code 3	Code 4	Code 5	Code 6	Code 7	Code 8	Code 9	Code 10
	Mfg. Year	Mfg. Month	Mfg. Date	Consecuti	ve number		Special code	•
Internal Tracing Code	2020-L 2021-M 2022-P 2023-Q  2026-T 2027-V  2030-Y 2031-Z	1:Jan. 2:Feb.  A:Oct. B:Nov. C:Dec.	1:A 2:B 3:C  26:Z 27:7 28:8 29:9 30:3 31:4	01-	-ZZ		000~ZZZ	

Official Product	HT Part No. B2601UYG-20C001023E0118				
Tentative Product	*******				
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, company confidential all rights reserved.		09/18/2023	Version 1.3	Page 5/14	



# **Specifications Range**

# ■Luminous Intensity (Iv) Bin:

Color	Bin Code	Spec. Range
	N	28.50-45.00 mcd
111/0	Р	45.00-71.50 mcd
UYG	Q	71.50-112.5 mcd
	R	112.5-180.0 mcd

Note: It maintains a tolerance of ±10% on Luminous Intensity

# ■Wavelength Bin:

Color	Bin Code	Spec. Range
	С	567.5-570.5 nm
10/0	D	570.5-573.5 nm
UYG	E	573.5-576.5 nm
	F	576.5-579.5 nm

Note: It maintains a tolerance of ±0.5nm on Wavelength Bin

# ■Forward Voltage (Vf) Bin:

Color	Bin Code	Spec. Range
UYG	E18	1.6-2.4 V

Note: It maintains a tolerance of ±0.05V on forward voltage measurements

Official Product	HT Part No. B2601UYG-20C001023E0118				
Tentative Product	*******				
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, company confidential all rights reserved.		09/18/2023	Version 1.3	Page 6/14	



#### **Product Features**

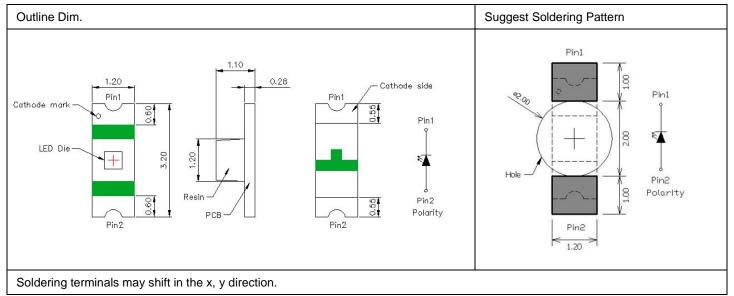
## **Electro-Optical Characteristics**

(T<sub>Soldering</sub>, 25 °C)

	Sorios Emitting Color		eries Emitting Color Material		Wavelength λ(nm)			I <sub>V</sub> (mcd)	Viewing	
Series	Emitting Color	olor Material	typ	max	$\lambda_{D}$	$\lambda_{P}$	$\triangle \lambda$	Typical	Angle $2\theta \frac{1}{2}$	
	B2601UYG-20	UYG	AlGaInP	2.1	2.4	571	573	15	71.5	140

# Package Outline Dimension and Recommended Soldering Pattern for Reflow Soldering

(Unit:mm Tolerance: +/-0.1)



# Absolute Maximum Ratings

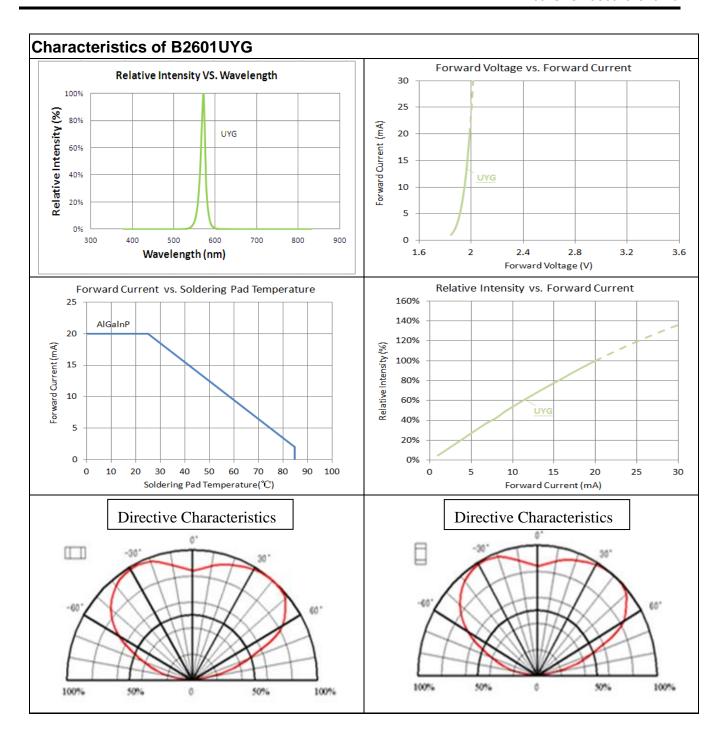
(T<sub>Soldering</sub> 25  $^{\circ}$ C)

Series	P <sub>D</sub> (mW)	I <sub>F</sub> (mA)	I <sub>FP</sub> (mA)*	T <sub>OP</sub> (°C)	T <sub>ST</sub> (°C)
Color	Dower Discipation	Forward Current	Pulse Forward	Operating	Storage
Color	Power Dissipation	Forward Current	Current	Temperature	Temperature
UYG	48	20	100	-40~+85	-40~+100

<sup>\*</sup>Condition for I<sub>FP</sub> is pulse of 1/10 duty and 0.1msec width

Official Product	t HT Part No. B2601UYG-20C001023E0118				
Tentative Product	*******				
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, company confidential all rights reserved.		09/18/2023	Version 1.3	Page 7/14	





7					
Official Product	HT Part No. B2601UYG-20C001023E0118				
Tentative Product	********	********			
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, company confidential all rights reserved.		09/18/2023	Version 1.3	Page 8/14	



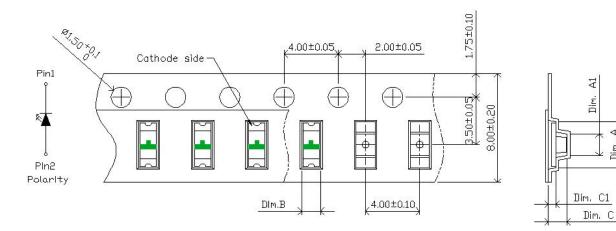
#### **Precaution for Use**

- 1. The chips should not be used directly in any type of fluid such as water, oil, organic solvent, etc.
- 2. When the LEDs are illuminating, the maximum ambient temperature should be first considered before operation.
- 3. LEDs must be stored in a clean environment. A sealed container with a nitrogen atmosphere is necessary if the storage period is over 3 months after shipping.
- 4. The LEDs must be used within 4 weeks after unpacked. Unused products must be repacked in an anti-electrostatic package, folded to close any opening and then stored in a dry and cool space.
- 5. The appearance and specifications of the products may be modified for improvement without further notice.
- 6. The LEDs are sensitive to the static electricity and surge. It is strongly recommended to use a grounded wrist band and anti-electrostatic glove when handling the LEDs. If a voltage over the absolute maximum rating is applied to LEDs, it will damage LEDs. Damaged LEDs will show some abnormal characteristics such as remarkable increase of leak current, lower turn-on voltage and getting unlit at low current.

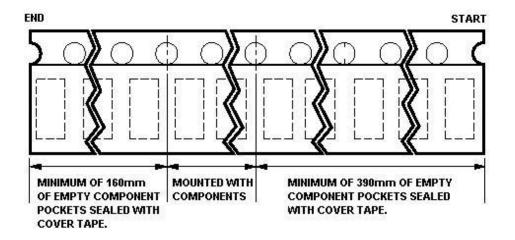
7					
Official Product	HT Part No. B2601UYG-20C001023E0118				
Tentative Product	*********				
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, company confidential all rights reserved.		09/18/2023	Version 1.3	Page 9/14	



# Packaging Tape Dimension



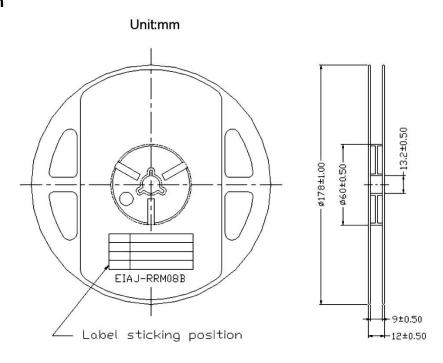
Dim. A	Dim. B	Dim. C	Qty/Reel
3.40±0.1	1.42±0.1	1.37±0.1	3K



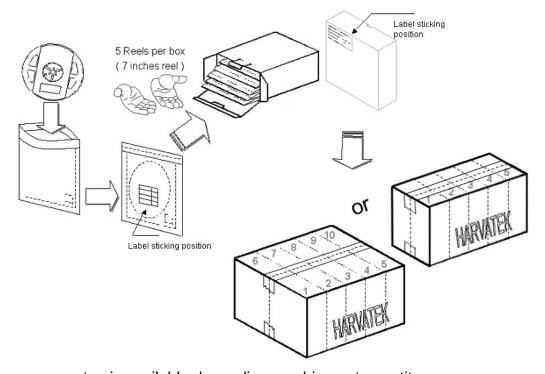
7					
Official Product	HT Part No. B2601UYG-20C001023E0118				
Tentative Product	*********	*******			
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, company confidential all rights reserved.		09/18/2023	Version 1.3	Page 10/14	



## **Reel Dimension**



# **Packing**



5 or 10 boxes per carton is available depending on shipment quantity.

Official Product	sial Product HT Part No. B2601UYG-20C001023E0118				
Tentative Product	********	*******			
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, company confidential all rights reserved.		09/18/2023	Version 1.3	Page 11/14	

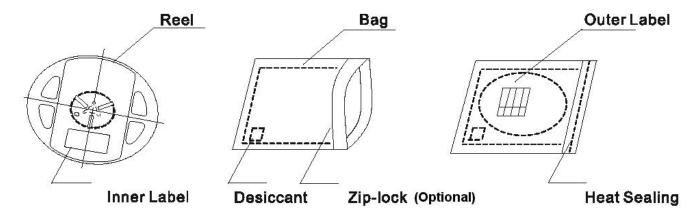


#### **Dry Pack**

All SMD optical devices are **MOISTURE SENSITIVE**. Avoid exposure to moisture at all times during transportation or storage. Every reel is packaged in a moisture protected anti-static bag. Each bag is properly sealed prior to shipment.

A humidity indicator will be included in the moisture protected anti-static bag prior to shipment.

The packaging sequence is as follows:



#### **Baking**

Baking before soldering is recommended when the package has been unsealed for 4 weeks.

The conditions are as followings:

- 1.  $60\pm3$ °C×(12~24hrs)and<5%RH, taped reel type.
- 2.  $100\pm3^{\circ}$  × (45min~1hr), bulk type.
- 3.  $130\pm3$ °C×(15min~30min), bulk type.

#### **Precautions**

- 1. Avoid exposure to moisture at all times during transportation or storage.
- 2. Anti-Static precaution must be taken when handling GaN, InGaN, and AlGaInP products.
- 3. It is suggested to connect the unit with a current limiting resistor of the proper size. Avoid applying a reverse voltage beyond the specified limit.
- 4. Avoid operation beyond the limits as specified by the absolute maximum ratings.
- 5. Avoid direct contact with the surface through which the LED emits light.
- 6. If possible, assemble the unit in a clean room or dust-free environment.

Official Product HT Part No. B2601UYG-20C001023E0118					
Tentative Product	*******	********			
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, company confidential all rights reserved.		09/18/2023	Version 1.3	Page 12/14	

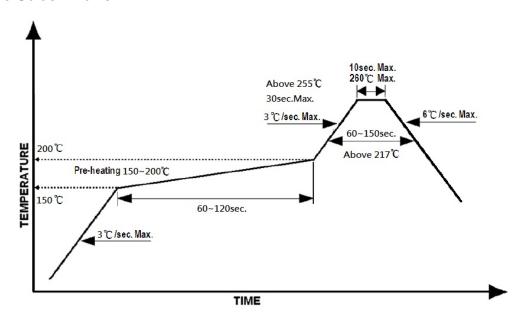


#### **Reflow Soldering**

Recommend soldering paste specifications:

- 1. Operating temp.: Above 217°C ,60~150 sec.
- 2. Peak temp.:260 °C Max.,10sec Max.
- 3. Reflow soldering should not be done more than two times.
- 4. Never attempt next process until the component is cooled down to room temperature after reflow.
- 5. The recommended reflow soldering profile (measured on the surface of the LED terminal) is as following:

Lead-free Solder Profile



#### Reworking

- Rework should be completed within 5 seconds under 260℃.
- The iron tip must not come in contact with the copper foil.
- Twin-head type is preferred.

#### Cleaning

Following are cleaning procedures after soldering:

- An alcohol-based solvent such as isopropyl alcohol (IPA) is recommended.
- Temperature x Time should be 50°C x 30sec. or <30°C x 3min</li>
- Ultrasonic cleaning: < 15W/ bath; bath volume ≤ 1liter</li>
- Curing: 100°C max, <3min</li>

Official Product	HT Part No. B2601UYG-20C001023E0118				
Tentative Product	********				
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, company confidential all rights reserved.		09/18/2023	Version 1.3	Page 13/14	



# **Cautions of Pick and Place**

- Avoid stress on the resin at elevated temperature.
- Avoid rubbing or scraping the resin by any object.
- Electric-static may cause damage to the component. Please ensure that the equipment is properly grounded. Use of an ionizer fan is recommended.

## **Revise History**

Rev.	Descriptions	Date	Page
1.0	-	02/07/2017	-
1.1	Renew form	01/15/2019	-
1.2	Renew form	02/24/2021	-
1.3	Renew form	09/18/2023	-

Official Product	HT Part No. B2601UYG-20C001023E0118			
Tentative Product	********	******		
Specifications are subject to changes for improvement without advance notice. Proprietary data, drawings, company confidential all rights reserved.		09/18/2023	Version 1.3	Page 14/14